



Customer Information Notification

202203003I : 5+1 Tray Packing Standardization at ATKH & ASEK

Note: This notice is NXP Company
Proprietary.

Issue Date: May 04, 2022 **Effective date:** Jun 08, 2022

Management summary

NXP will standardize the 5+1 Tray Dry-Pack Packing Methods.
This will result in different dimensions of the packing boxes.

Change Category

- | | | | | |
|--|--|---|--|---|
| ☐ Wafer
Fab
Process | ☐ Assembly
Process | ☐ Product Marking | ☐ Test
Process | ☐ Design |
| ☐ Wafer
Fab
Materials | ☐ Assembly
Materials | ☐ Mechanical
Specification | ☐ Test
Equipment | ☐ Errata |
| ☐ Wafer
Fab
Location | ☐ Assembly
Location | ☒ Packing/Shipping/Labeling | ☐ Test
Location | ☐ Electrical
spec./Test
coverage |
| ☐ Firmware | ☐ Other | | | |

PCN Overview

Description

Currently in our assembly site ATKH at Kaohsiung Taiwan and our subcon ASEK at Kaohsiung Taiwan 5+1 dry-packed trays are packed using three designs of packing boxes.

These three packing methods will be replaced with one packing method as used in our ATKL (Kuala Lumpur) and ATTJ (Tianjin) assembly site.

See attached document to which explains the details.

This change will be implemented in week 23 of 2022, based on the Sealed Date of PQ Label.

Reason

NXP wants to standardize to one 5+1 dry-packing method for trays.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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